Packaging Substrate

**DESCRIPTION**

Fujitsu Interconnect Technologies Limited (FICT) provides design, manufacturing, maintenance, and consulting services for substrate packages.

As the functionality and performance of network systems, high-end servers, and mobile communication devices improves, the demand for high-performance, high pin count packages is increasing. This increasing demand requires new technologies, which incorporate high pin count and also delivers performance via impedance control, low crosstalk, DC/AC resistance, and low VG impedance. Sophisticated interconnect technology has become essential for meeting these needs by improving the density and reliability of the substrates for LSI package and module boards.

Fujitsu has been a technology leader in this area for a long time. FICT’s GigaModule technology is available in a series of GigaModule product lines. FICT has incorporated several new technologies, materials and processes in these product lines to meet the market requirements at competitive pricing. These products are available in both flip chip and wire bond interconnection with variety of configurations. In addition we are developing next generation packages, which are expected to significantly improve performance and reduce costs.

**PRODUCT OFFERINGS**

Packaging Substrate Manufacturing
- ASIC, FPGA, and graphics
- Build-up substrate from 1-2-1 to 6-2-6
- 20 µm Line and Space (15 µm is proto)
- Coreless structure (Proto)
- 2500 pins substrate is under production
- Low CTE, High Modulus, Low loss materials

Substrate Design Services
Simulation Services
Custom Project
- Layer reduction

**WHY FICT?**

Technology leader
- Design
- Processes
- Materials
- Manufacturing

Proven quality at all plants
Global presence and support
Environmentally sensitive design and manufacturing
R&D commitment
Factory expansion and renovation
Long term and reliable partner
## Features

- Coreless structure
- Advanced materials
- High density wiring by stacked via

## Benefits

- Cost reduction
- Time reduction
- Layer count reduction
- High yield
- Increased throughput
- High-speed transmission
- Size reduction

## Technology

- Stacked build-up technology
- Coreless technology with low loop inductance
- Impedance control
- Crosstalk design in
- Improved materials for both mechanical and electrical properties

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**FICT Factories approved by over 35 Customers**

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**FUJITSU INTERCONNECT TECHNOLOGY**

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